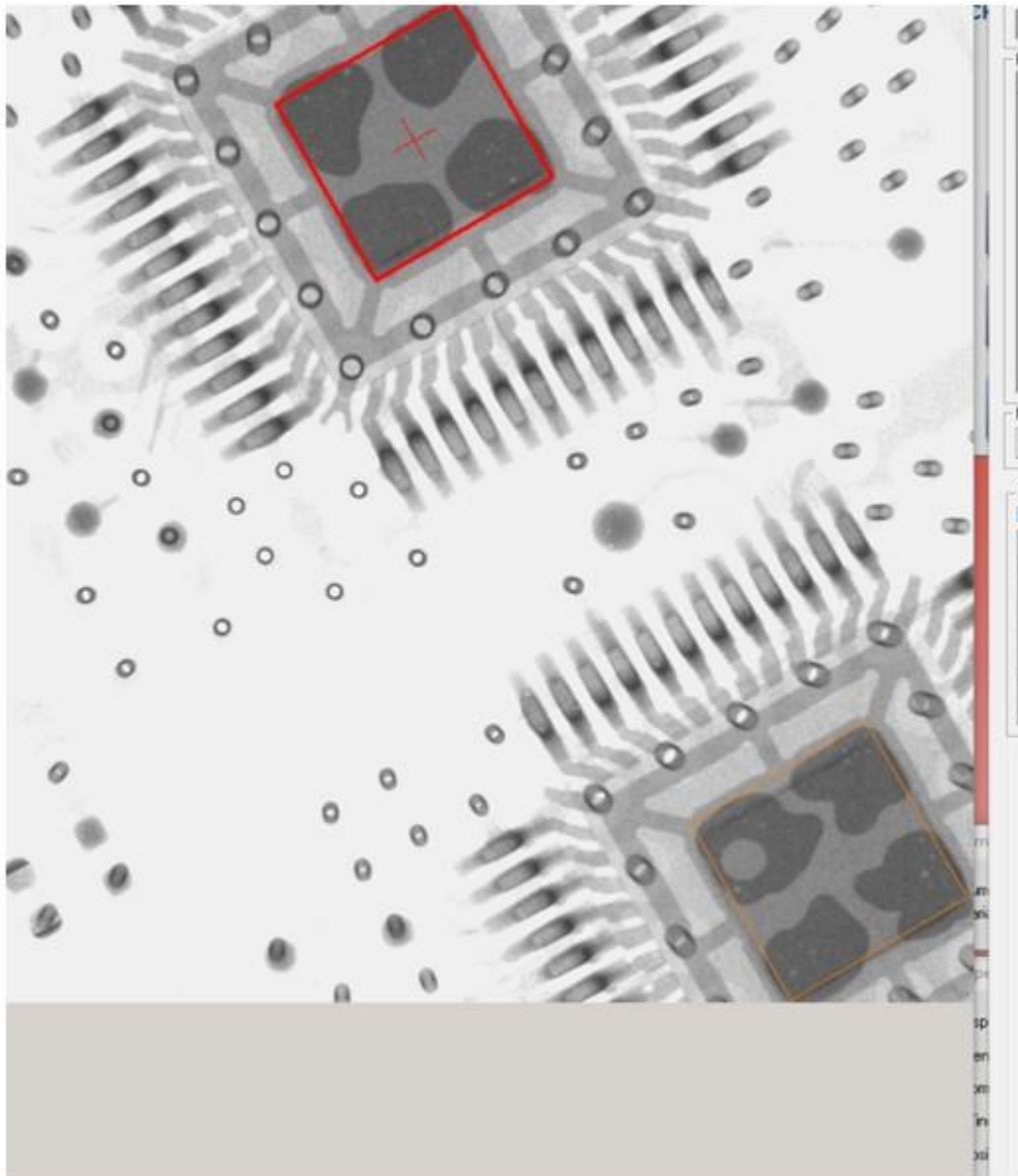


Voids issue on the thermal pad:



Solderability test results:

